

Product Change Notification - LIAL-08UVRX401

Date:

23 Jan 2019

Product Category:

Others: Ethernet Controllers

Affected CPNs:



Notification subject:

CCB 3285 Final Notice: Qualification of ASE as a new assembly site for selected products of the 0.18um wafer technology at DBHU available in 48L LQFP (7x7x1.4mm) package.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of ASE as a new assembly site for selected products of the 0.18um wafer technology at DBHU available in 48L LQFP (7x7x1.4 mm) package.

Pre Change:

Assembled at TICP assembly site using CEL-9200 mold compound material

Post Change:

Assembled at ASE assembly site using EME-G631H mold compound material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Taiwan IC Packing Corp. (TICP)	ASE Inc. (ASE)
Wire material	Au	Au
Die attach material	EN4900	EN4900
Molding compound material	CEL-9200	EME-G631H
Lead frame material	C7025	C7025

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying ASE as new assembly site

Change Implementation Status:

In Progress

Estimated First Ship Date:

February 23, 2019 (date code: 1908)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2018					,	January 2019					February 2019			
Workweek	09	10	11	12	13	'\	01	02	03	04	05	06	07	80	09



Initial PCN Issue Date			X						
Qual Report						_			
Availability						^			
Final PCN Issue Date						X			
Estimated								V	
Implementation Date								^	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report

Revision History:

March 28, 2018: Issued initial notification.

April 20, 2018: Re-issued initial notification to update the Qual plan and to correct the date on initial notification revision history.

April 30, 2018: Re-issued initial notification to correct the attachment for the affected CPN list. January 23, 2019: Issued final notification. Added the qualification report and estimated first ship date by February 23, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_LIAL-08UVRX401_QUAL_REPORT.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

KSZ8851-16MLL

KSZ8851-16MLLI

KSZ8851-16MLLI-TR

KSZ8851-16MLLJ

KSZ8851-16MLL-TR

KSZ8851-16MLLU

KSZ8851-16MLLU-TR

SPNY801062

SPNZ801062

Date: Tuesday, January 22, 2019